ULTRA-LOW PROFILE MICRO ARRAYS

SPECIFICATIONS
For complete specifications and recommended PCB layouts see www.samtec.com/ZA1

Insulator Material: FR4
Contact Material: BeCu
Plating: Au over 50 µ" (1.27 µm) Ni
Current Rating: 1 A per pin
(10 pins powered)

Operating Temp Range:
-55 °C to +105 °C

RoHS Compliant: Yes

APPLICATION

Dual compression or single compression with solder balls

HIGH-SPEED CHANNEL PERFORMANCE

1 mm Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

14 Gbps

DESIGN FLEXIBILITY

The Z-Ray® platform is highly-customizable:

PITCH ≥ 0.65 mm
STACK HEIGHT 0.50 mm to 4.00 mm
DENSITY Up to 1,024 contacts/square inch
RUGGEDIZING Latches, Thermal Spreaders, Quick-release Spring Constraints
CONSTRUCTION Multi-layer FR4 (e.g., Pitch Spreaders)

Note:
Some lengths, styles and options are non-standard, non-returnable.

APPLICATION

ZA1 POSITIONS PER ROW
-10, -20, -30, -40

TERMINATION
-1 = Single Compression with Solder Balls (-10 & -20 positions only)
-2 = Dual Compression (-10, -20, -30 & -40 positions only)

HEIGHT
-10 = -1.00 = (1.00 mm) .040" Height

PLATING -Z = 6 µ" (0.15 µm) Gold in contact area

ROWS -10 = Ten Rows

SOLDER TYPE -1 = Lead
-2 = Lead-Free

Solder ball option

Note:
Solder ball parts will come with a pick & place pad.

Due to technical progress, all designs, specifications and components are subject to change without notice.

www.SAMTEC.COM

All parts within this catalog are built to Samtec’s specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.